

PCN Number:	20180111003	PCN Date:	January 19, 2018
Title:	Datasheet for TMP20		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.

TMP20



SBOS466A – DECEMBER 2009 – REVISED OCTOBER 2017

Changes from Original (December 2009) to Revision A	Page
• Updated data sheet formatting and content to latest TIS documentation and translation standards	1
• Added body size information to <i>Device Information</i> section	1
• Updated Device Block Diagram	1
• Updated Device Quiescent Current Over Temperature	1
• Reformatted <i>Absolute Maximum Ratings</i> table	4
• Changed <i>Thermal Information</i> table and added thermal information	4
• Changed minimum temperature sensitivity value from -11.4 mV/°C to -12.2 mV/°C in <i>Electrical Characteristics</i> table	5
• Changed maximum temperature sensitivity value from -12.2 mV/°C to -11.4 mV/°C in <i>Electrical Characteristics</i> table	5
• Updated Figure 1	6
• Updated Figure 3	6
• Updated Figure 7	6
• Added <i>Functional Block</i> diagram, key graphics on front page, typical application schematic, application curves, and updated layout images	8
• Reformatted equations in <i>Transfer Function</i> section	9
• Corrected Equation 2 in <i>Transfer Function</i> section	9
• Added copyright notices to Figure 15 and Figure 16	14

Note: The word “updated” in the Revision History refers to a formatting change for the following items:

- Updated Device Block Diagram
- Updated Device Quiescent Current Over Temperature
- Updated Figure 1, Figure 3, and Figure 7

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP20	SBOS466	SBOS466A

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/INA138>

Reason for Change:

Added thermal metric specifications; Datasheet reformatting change.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. There are no changes to the actual device.

Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
TMP20AIDCKR	TMP20AIDCKT	TMP20AIDRLR	TMP20AIDRLT

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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Asia Pacific	PCNAsiaContact@list.ti.com
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